test is performed on the circuit. The circuit test determines a first and a second test condition of the circuit. testing apparatus comprises a positioning apparatus having a first port and a second port. The positioning apparatus is capable of displacement to a first position and a second position. The first port receives the circuit for testing. The testing apparatus further comprises a testing apparatus for securing the circuit during a testing of the circuit when the positioning apparatus is displaced to the second position during the testing. The testing apparatus further comprises a testing control pin for retaining the circuit in the first port prior to the testing and for allowing a transfer of the circuit from the first port to said second port subsequent to the testing. Finally, the testing apparatus comprises a first and a second track. The first track receives the circuit from the second port when the circuit test finds the circuit to have the first test condition, the positioning apparatus being in the first position, and the second track receives the circuit from the second port when the circuit test finds the circuit to have the second test condition, the positioning apparatus being in the second position. A control pin is used for retention and release of the circuit in and from, respectively, the first and second ports. ---

In the Claims:

Kindly cancel claims 2-4, 6-7 and 9-12.

Kindly amend the following claims:

1. (once amended) An [IC] <u>integrated circuit</u> testing apparatus [(11) that will test ICs] <u>for testing an integrated circuit</u> leaving an IC singulation [apparatus (44)] <u>station</u>, comprising:

[coupling means for operatively coupling the IC singulation apparatus (44) to the IC testing apparatus (11);]

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a) a receiving means [(16)], positioned in a pre test position for receiving [ICs] the integrated circuit from the IC singulation station;

b) a testing [means(18)] site, positioned to [receive ICs from the receiving means for electrically testing the ICs and identifying defective and non-defective ICs] secure the integrated circuit after a displacement of said receiving means to a test position, the displacement positioning said integrated circuit in said testing site said test site having a test connection for making physical contact with said integrated circuit when it is secured in said testing site, a circuit test performed on said integrated circuit when it is secured in said testing site; and

[separating means (34), operatively coupled to the testing means, for separating the defective and non-defective ICs]

a holding station having a first post test position and a second post test position, said holding station receiving the integrated circuit in said first post test position from the receiving means following a return of

the receiving means to said pre test position subsequent to the performing of the circuit test the integrated circuit:



- d) a first track for receiving the integrated circuit from the holding station when the holding station is in said first post test position and when the circuit test determines that the integrated circuit has a first test condition; and
- e) a second track for receiving the integrated circuit from the holding station when the holding station is in said second post test position, said second test position attained when said receiving means returns to said test position, said second track receiving the integrated circuit when the circuit test determines that the integrated circuit has a second test condition.

(once amended) The [device] apparatus of claim [4] 1, wherein the holding station further [comprising] comprises:

[the holding station, while] a control pin for retaining the integrated circuit in the first post test position, [will hold defective ICs from proceeding to the separating means,

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and allow non-defective ICs to proceed to the non-defective IC track (36) in the separating station; and

the holding station, while in the second position, will release defective ICs to the defective IC track (38) in the separating station] when the integrated circuit has said second test condition, and for releasing the integrated circuit from the first post test position to said first track when said integrated circuit has said first test condition, and for releasing said integrated circuit from said second post test position to said second track when said integrated circuit has said integrated circuit has said second track when said integrated circuit has said second test condition.

(once amended) A method for [IC] testing an integrated circuit [that uses an IC] in a testing apparatus [for testing ICs that are leaving] after a departure of the integrated circuit from an [IC] integrated circuit singulation apparatus [(44)], comprising the steps of:

[operatively coupling the IC singulation apparatus (44) to the IC testing apparatus (11);

receiving, onto the testing apparatus, singulated ICs from the IC singulation station;]

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- a) moving the testing apparatus to a loading position;
- b) loading the integrated circuit into the testing apparatus;
- c) moving the testing apparatus to a test position to position the integrated circuit for testing;
- d) performing [electrically testing] electrical tests on the [singulated ICs and identifying] integrated circuit to provide a tested integrated circuit having identified [defective and non-defective ICs; and] first and second test conditions;
- e) moving the testing apparatus from the test position to position the tested integrated circuit for unloading;
- f) moving the tested integrated circuit to a first unloading position;
- g) unloading the tested integrated circuit from the first unloading position to a first track when it has said first test condition:
- h) moving the tested integrated circuit to a second

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unloading position when it has said second test condition; and

i) unloading the tested integrated circuit from the second unloading position to a second track when it has said second test condition.

Kindly add the following claims:

The method as specified in Claim 8, further comprising moving said testing apparatus to said test position during said step of moving the tested integrated circuit to said second unloading position.

A testing apparatus for controlling positioning of a circuit before, during and after a circuit test is performed on the circuit, the circuit test determining a first and a second test condition of the circuit, the apparatus comprising:

a) a positioning apparatus having a first port and a second port and capable of displacement to a first position and a second position, said first port receiving the circuit for testing;

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- b) a testing apparatus for securing said circuit during a testing of the circuit, said positioning apparatus displaced to said second position during the testing;
- c) a testing control pin for retaining said circuit in said first port prior to the testing and for allowing a transfer of said circuit from said first port to said second port subsequent to the testing;
- d) a first track for receiving said circuit from said second port when said circuit test finds said circuit to have the first test condition, said positioning apparatus being in said first position; and
- e) a second track for receiving said circuit from said second port when said circuit test finds said circuit to have the second test condition, said positioning apparatus being in said second position.

The method as specified in Claim 14, further comprising an unloading control pin for retaining said circuit in said second port when said circuit test finds said circuit to have said second test condition and said testing apparatus is in said first position and for allowing a release of said circuit to said first track when

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said circuit test finds said circuit to have said first test condition and for allowing a release of said circuit to said second track when said circuit test finds said circuit to have said second test condition. --.

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